

FIG. 1

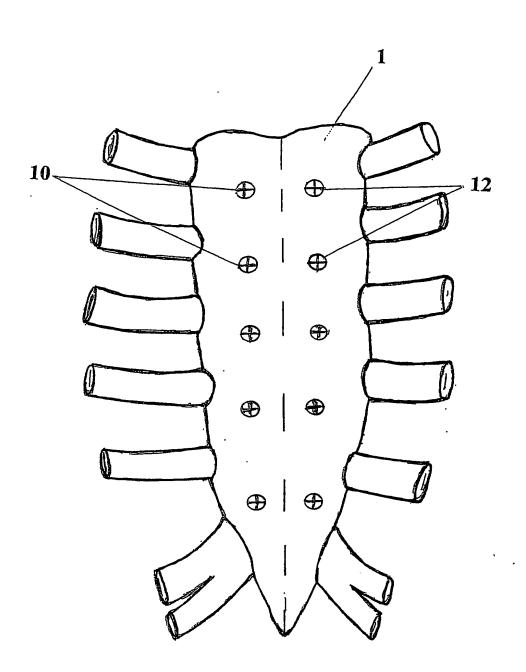


FIG. 2

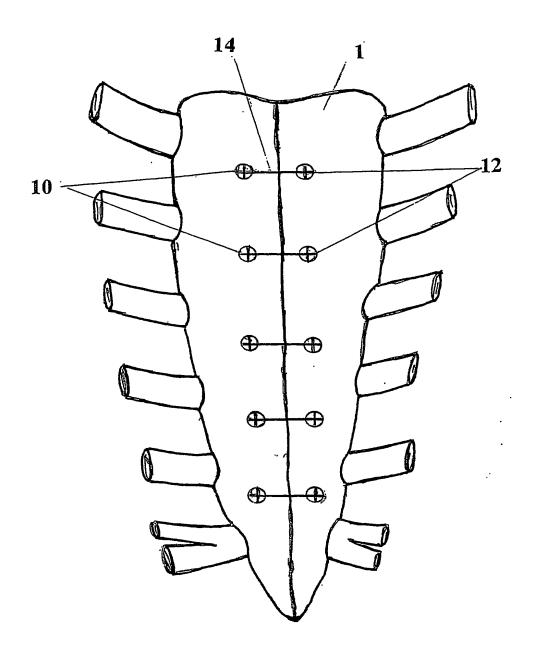


FIG. 3

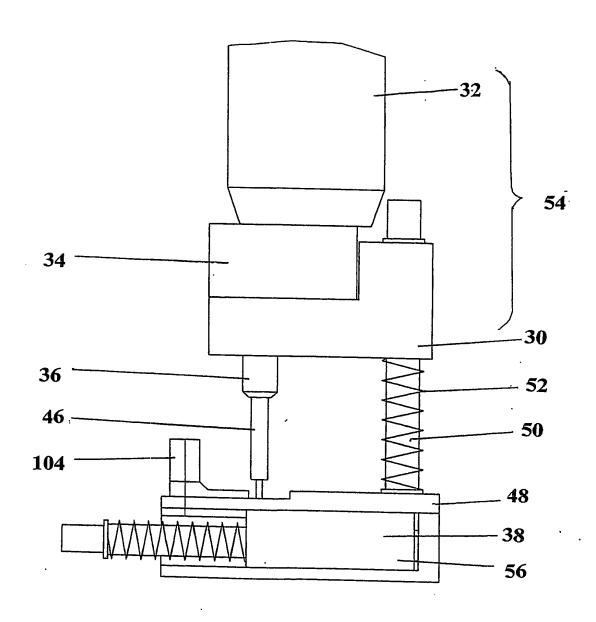


FIG. 4

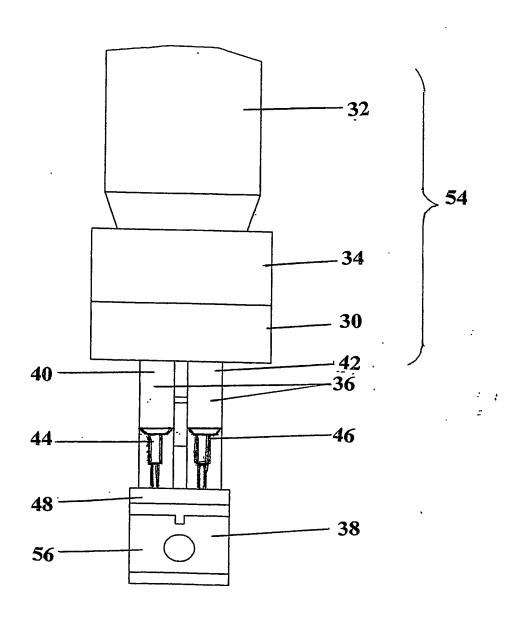
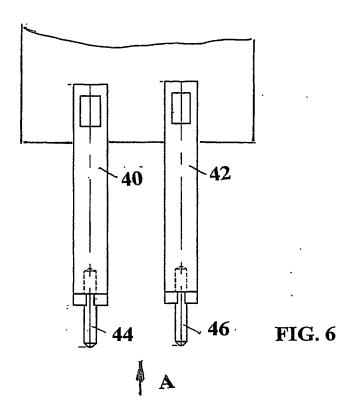


FIG. 5



View A

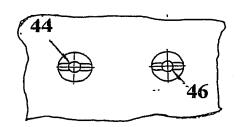
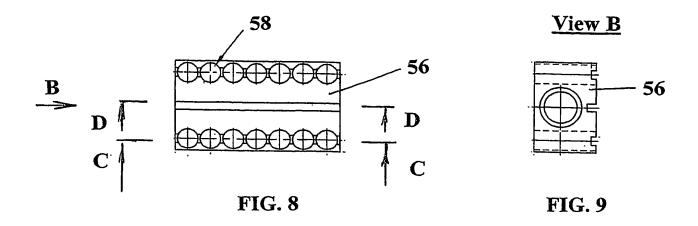


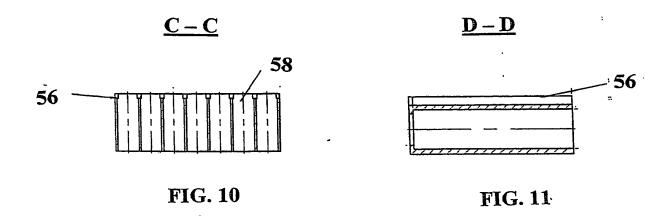
FIG. 7

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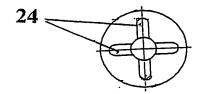


FIG. 12

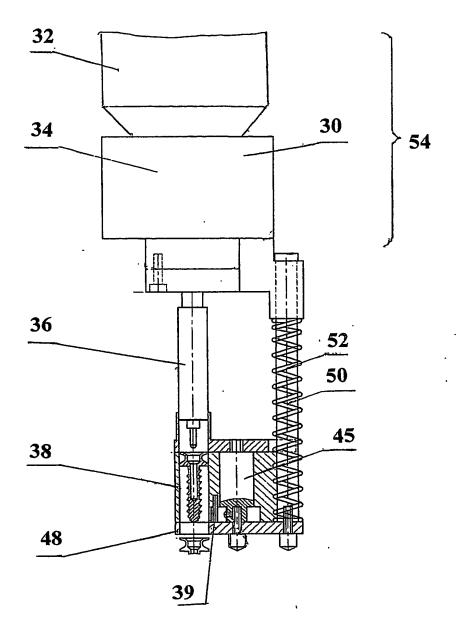


FIG. 13

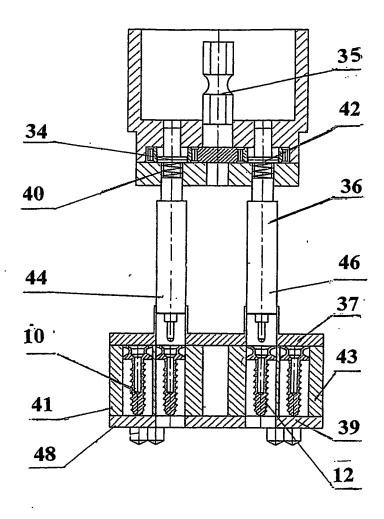


FIG. 14

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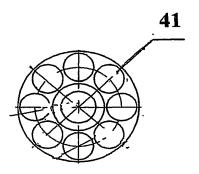


FIG. 15

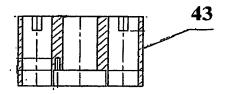


FIG. 16

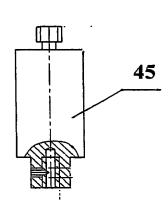


FIG. 17

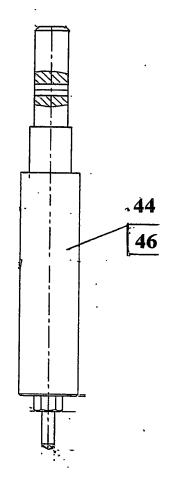


FIG. 18

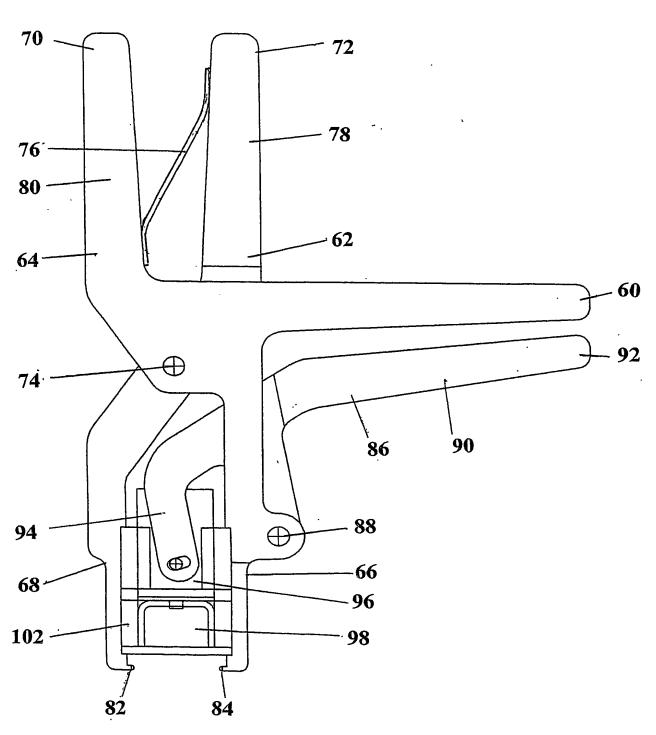


FIG. 19

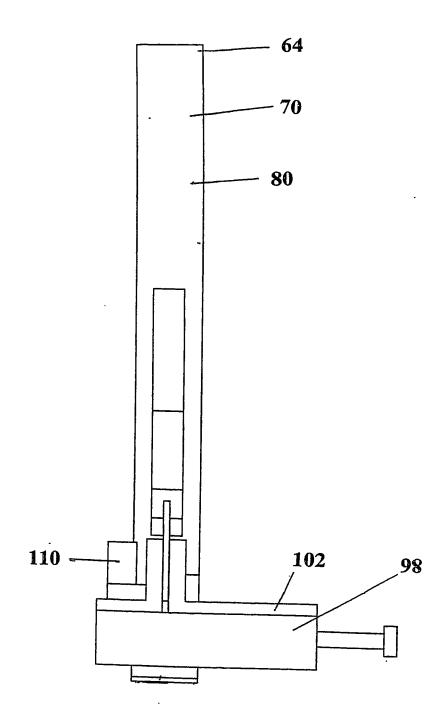


FIG. 20

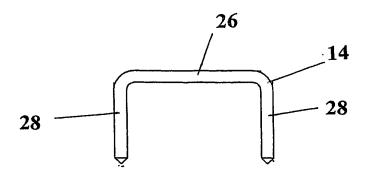
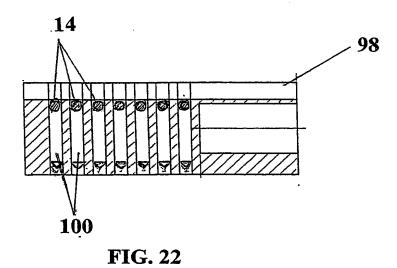
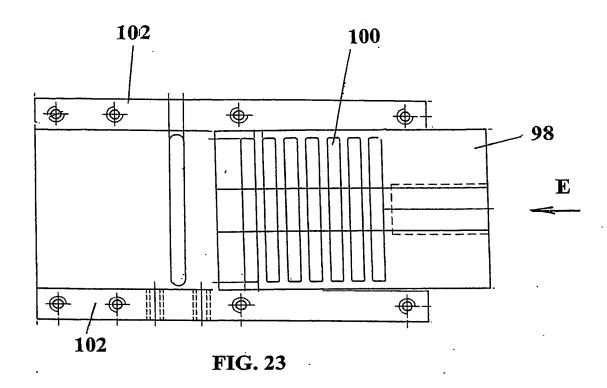


FIG. 21



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View E

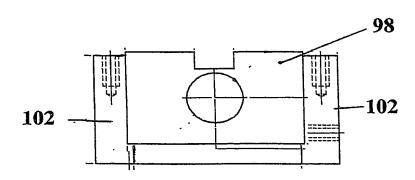


FIG. 24

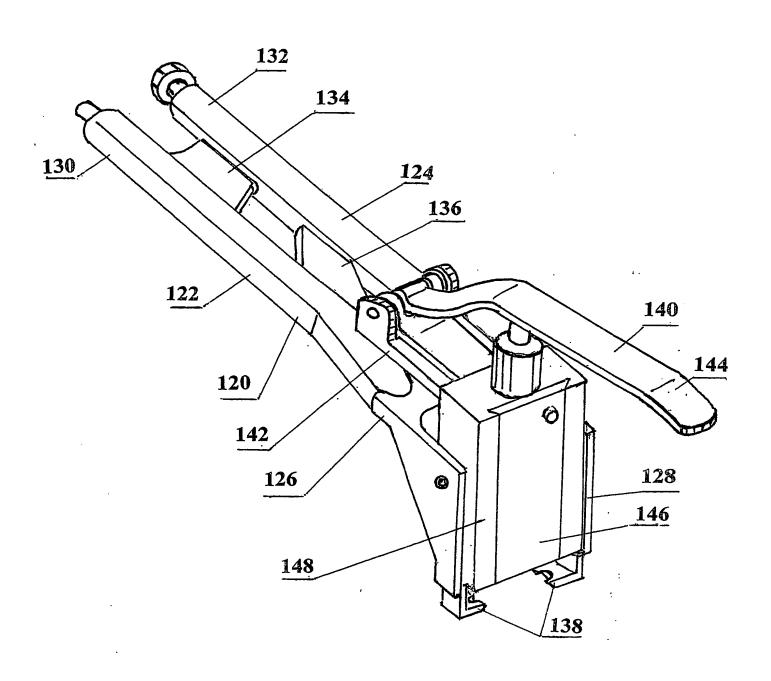


FIG. 25

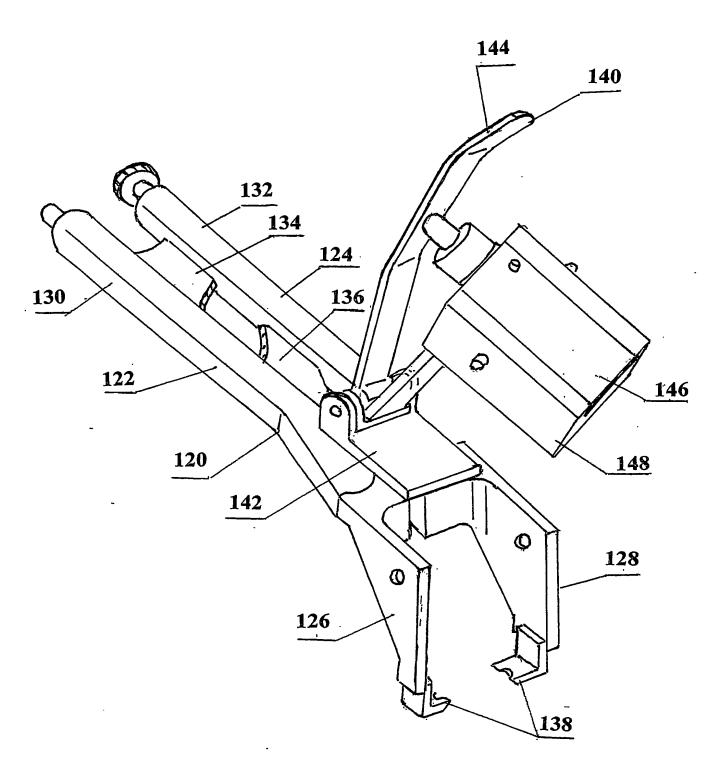


FIG. 26

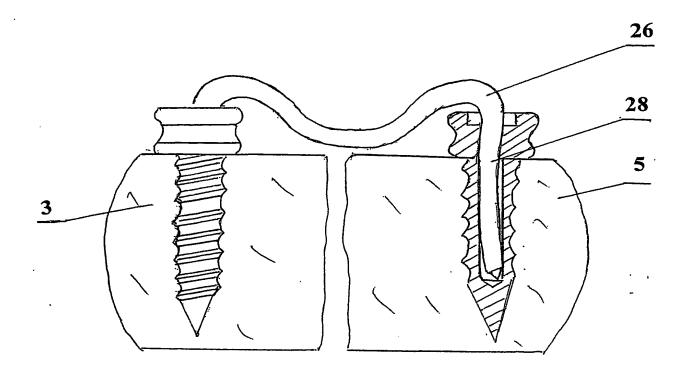
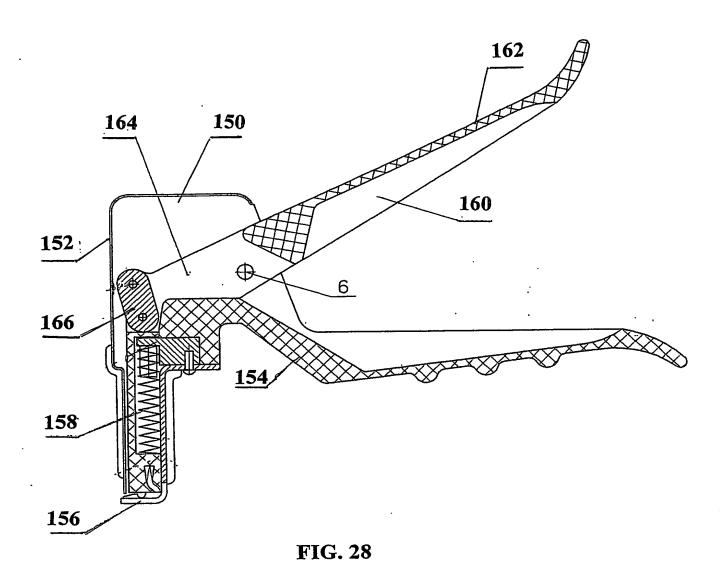


FIG. 27



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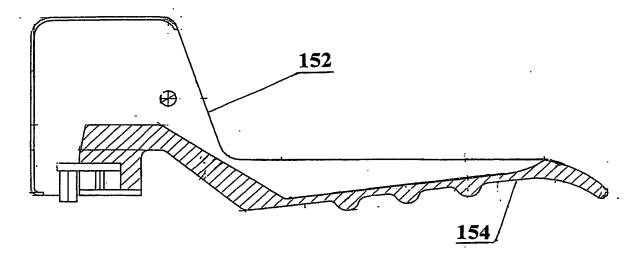


FIG. 29

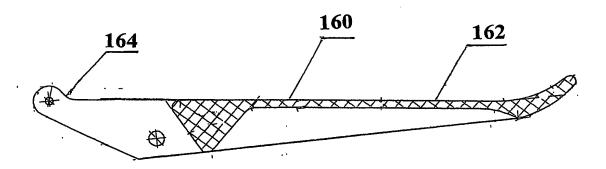


FIG. 30

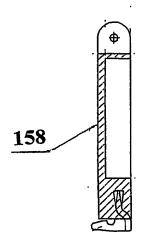


FIG. 31

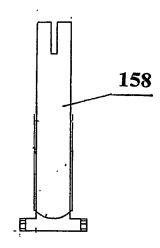


FIG. 32

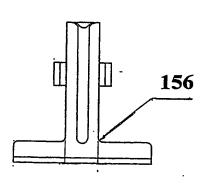


FIG. 33

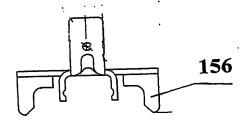


FIG. 34

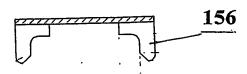


FIG. 35